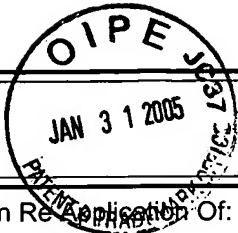


IFW



**TRANSMITTAL LETTER  
(General - Patent Pending)**

Docket No.  
**END920010135US2**

In Re Application Of: **Alcoe et al.**

Application No.	Filing Date	Examiner	Customer No.	Group Art Unit	Confirmation No.
10/665,669	9/18/2003	Thao X. Le	30449	2814	

Title: **THERMALLY ENHANCED LID FOR MULTI-CHIP MODULES**

COMMISSIONER FOR PATENTS:

Transmitted herewith is:

- Request for Reconsideration (14 pages)**
- Replacement Sheet (Fig. 6)**

in the above identified application.

- ☒ No additional fee is required.
  - ☐ A check in the amount of \_\_\_\_\_ is attached.
  - ☒ The Director is hereby authorized to charge and credit Deposit Account No. **09-0457(IBM)** as described below.
    - ☐ Charge the amount of \_\_\_\_\_
    - ☒ Credit any overpayment.
    - ☒ Charge any additional fee required.
  - ☐ Payment by credit card. Form PTO-2038 is attached.
- WARNING: Information on this form may become public. Credit card information should not be included on this form. Provide credit card information and authorization on PTO-2038.**

*Jack P. Friedman*  
Signature

Dated: 01/25/2005

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I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to the "Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450" [37 CFR 1.8(a)] on
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<i>Kim Dwileski</i> Signature of Person Mailing Correspondence
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cc: